

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	21JUL21	A.UY
B	AS PER ECR-109977	15SEP22	A.UY
C	AS PER ECR-111700	24NOV22	A.UY

ASSEMBLY NOTES:

- BOARD ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00119 (LATEST REVISION).
- REPAIRS PER IPC-7711/21(LATEST REVISION) ARE ALLOWED.
- REPAIRS ARE NOT ALLOWED IN SOLDERMASK FREE AREAS ON EITHER SIDE OF THE BOARD.
- RoHS COMPLIANCE: ASSEMBLY VENDOR SHOULD ASSURE COMPLIANCE WITH LEAD-FREE AND RoHS PCB ASSEMBLY STANDARDS (EU RoHS DIRECTIVE 2002/95/EC).
- ADD CONTROL KNOB (N059034) TO THE SHAFT OF S1.

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM TOLERANCES DECIMALS FRACTIONS ANGLES .XX -.010 --1/32 -- 2 .XXX -.005 .XXX -.0050	APPROVAL	DATE	<div><div></div><div>ANALOG DEVICES</div></div> <div>WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887</div>			
	TEMPLATE ENGINEER					
	HARDWARE SERVICES M.VALE	21JUL21	TITLE ASSEMBLY CUSTOMER EVAL Z EVAL-CN0359-EBZ			
	HARDWARE SYSTEMS					
MATERIAL	TEST ENGINEER					
FINISH	COMPONENT ENGINEER M.YAN	21JUL21	SIZE C	FSCM NO 24355	DRAWING NUMBER 01-059785	REV C
	TEST PROCESS					
	HARDWARE RELEASE K.JABATAN	21JUL21				
DO NOT SCALE DWG	DESIGNER G.GARCIA	21JUL21	SCALE 1/1	SHEET 1 OF 2		
	PTD ENGINEER A.UY	21JUL21				
	CHECKER					



SIZE	FSCM NO	DRAWING NUMBER	REV
C	24355	01-059785	C
SCALE	1/1	SHEET 2 OF 2	

ROHS COMPLIANCE NOTE: HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLIANT
THE EU RoHS DIRECTIVE 2002/95/EC

MATERIAL FAMILY; ISOLA370HR OR S1000-2 OR IT180 OR EQUIVALENT

CLADDING; EXTERNAL LAYERS .5 OZ. COPPER, OVERPLATE TO 1.5 OZ.

NOTE: IF THE LAYER STACKUP CONFLICTS WITH THE ABOVE
CLADDING SPECIFICATIONS THEN THE LAYER STACKUP SHALL
TAKE PRECEDENCE.

SOLDER MASK; SHALL BE LIQUID PHOTOIMAGEABLE (LPI) APPLIED ON BOTH SIDES
OVER BARE COPPER OR GOLD AND SHALL MEET IPC-SM-840
(LATEST REV.) CLASS 3. COLOR GREEN.

SILK SCREEN; SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK, COLOR: WHITE
SYNTHETIC INKJET PRINTING ALLOWED FOR DENSE BOARDS,
COLOR: WHITE

SURFACE FINISH; ENIG (ELECTROLESS NICKEL/IMMERSION GOLD)
PER IPC-4552 LATEST REVISION

INTENTIONAL SHORTS; IF SUPPLIED DATA INCLUDES A FILE "READ_ME.2", THEN
INTENTIONAL NET SHORTS EXIST. CUSTOMER REVIEW AND APPROVAL
IS REQUIRED IF SUPPLIED DATA REPORTS ANY CONDITION THAT
DOES NOT MATCH "READ ME.2" FILE PROVIDED.

TEST REQUIREMENTS; 100% NETLIST ELECTRICAL VERIFICATION USING CUSTOMER
SUPPLIED IPC-D-356 NETLIST FOR OPENS AND SHORTS WHEN
"GERBER DATA" IS PROVIDED. THIS VERIFICATION ALSO
REQUIRED FOR "ODB++" DATA PER EMBEDDED NETLIST.

Diagram illustrating the cross-section of a PCB, showing the layers and thicknesses:

- PRIMARY SILKSCREEN
- PRIMARY SOLDER MASK
- PRIMARY SIDE (LAYER 1)
- SECONDARY SIDE (LAYER 2)
- SECONDARY SOLDER MASK
- SECONDARY SILKSCREEN

The nominal finished thickness is indicated as 1.6 MM $\pm 10\%$.

UNLESS SPECIFIED
PLATED: ± 0.0762 MM.
NON PLATED: ± 0.0508 MM.

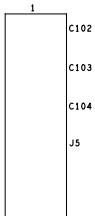
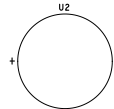
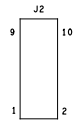
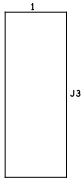
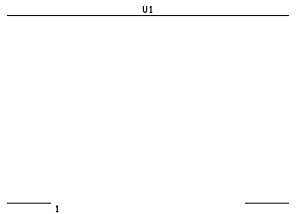
DRILL CHART: TOP to BOTTOM				
FINISHED HOLES IN MILLIMETERS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
•	0.254	PLATED	488	DIAMAX
◦	0.7112	PLATED	10	
◦	0.889	PLATED	19	
◦	1.016	PLATED	5	
◦	1.143	PLATED	10	
◦	1.27	PLATED	9	
◦	1.651	PLATED	2	
◦	1.905	PLATED	3	
◦	1.0414	NON-PLATED	4	
B	3.175	NON-PLATED	4	
O	2.667x2.159	PLATED	2	

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	TEMPLATE ENGINEER						
	DECIMALS FRACTIONS ANGLES .XX --.010 --1/32 -- 2 .XXX --.005 .XXXX --.0050	HARDWARE SERVICES M.VALE HARDWARE SYSTEMS					21JUL21
MATERIAL	TEST ENGINEER		TITLE FABRICATION CUSTOMER EVAL Z EVAL - CN0359 - EBZ				
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	CHECKER						
DO NOT SCALE DWG			SCALE	1/1		SHEET 1 OF 1	

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1. REFER TO IPC-6010 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
2. ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00115, (LATEST REVISION.)
3. MODIFICATIONS TO THE ARTWORK ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
4. HOLE PATTERN TOLERANCES FOR UNDIMENSIONED HOLES SHALL BE A DIAMETER OF 0.127 MM FROM THEIR TRUE POSITION.
5. PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN 0.0254 MM MINIMUM AVERAGE, WITH NO READING LESS THAN 0.02032 MM BY CROSS SECTION.
6. HOLE DIAMETERS APPLY AFTER PLATING.
7. FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
8. MINIMUM DESIGN LINE WIDTH IS .2032 MM.
9. MINIMUM DESIGN SPACING IS .1958 MM.
- ~~10. NON-FUNCTIONAL PAD REMOVAL FROM INNER SIGNAL LAYERS MAY BE PERFORMED AFTER CUSTOMER APPROVAL.~~
11. IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNULAR RING REQUIREMENT, MFR. MAY REQUEST APPROVAL TO TEAR DROP PADS TO MAINTAIN ANNULAR RING. (AT PAD TO TRACE INTERSECTION ONLY AND ELECTRICAL INTEGRITY MUST BE MAINTAINED.)
12. THIEVING MAY BE ADDED TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN ONLY AFTER REVIEW AND APPROVAL FROM THE CUSTOMER:
 - A. THIEVING TO CARD EDGE, FIDUCIALS, NON-PLATED THROUGH HOLES, ALL OTHER FEATURES TO BE 5.08 MM MINIMUM.
 - B. THERE SHALL BE NO THIEVING IN ANY AREAS FREE OF SOLDER MASK OR INTERNAL COPPER PLANES.
13. MFR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED;
 - A. U.L. CODE-FLAMMABILITY RATING
 - B. DATE CODE (STAMP).
 - C. LOT NUMBER
 - D. MFR LOGO
 - E. SUCCESSFUL ELECTRICAL TEST.
14. REPAIRS PER IPC-7711/21 (LATEST REV.) ARE ALLOWED.

SILKSCREEN PRIMARY
08-059785-03
REV C



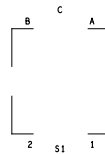
C2

C3

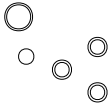
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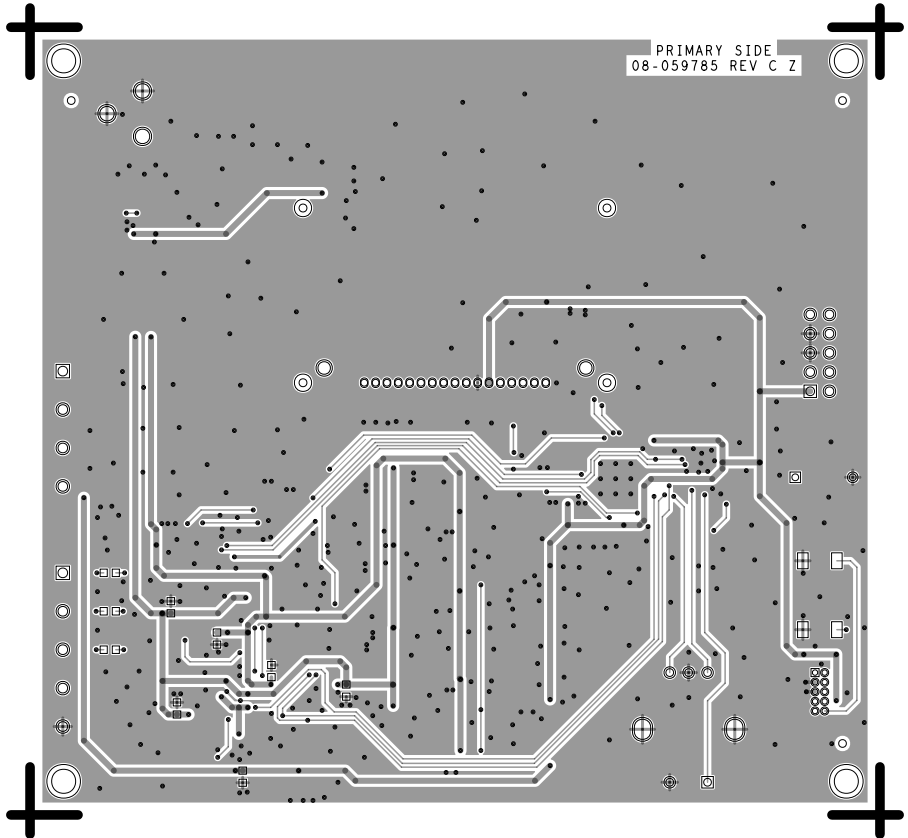
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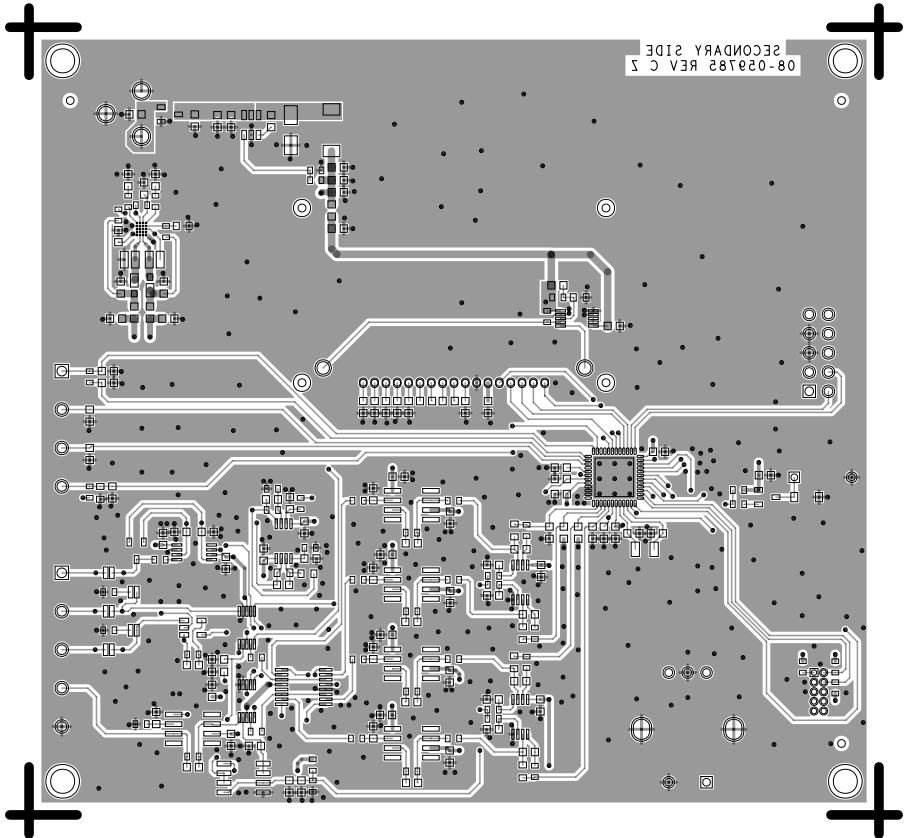
SOLDERMASK PRIMARY
08-059785-04
REV C



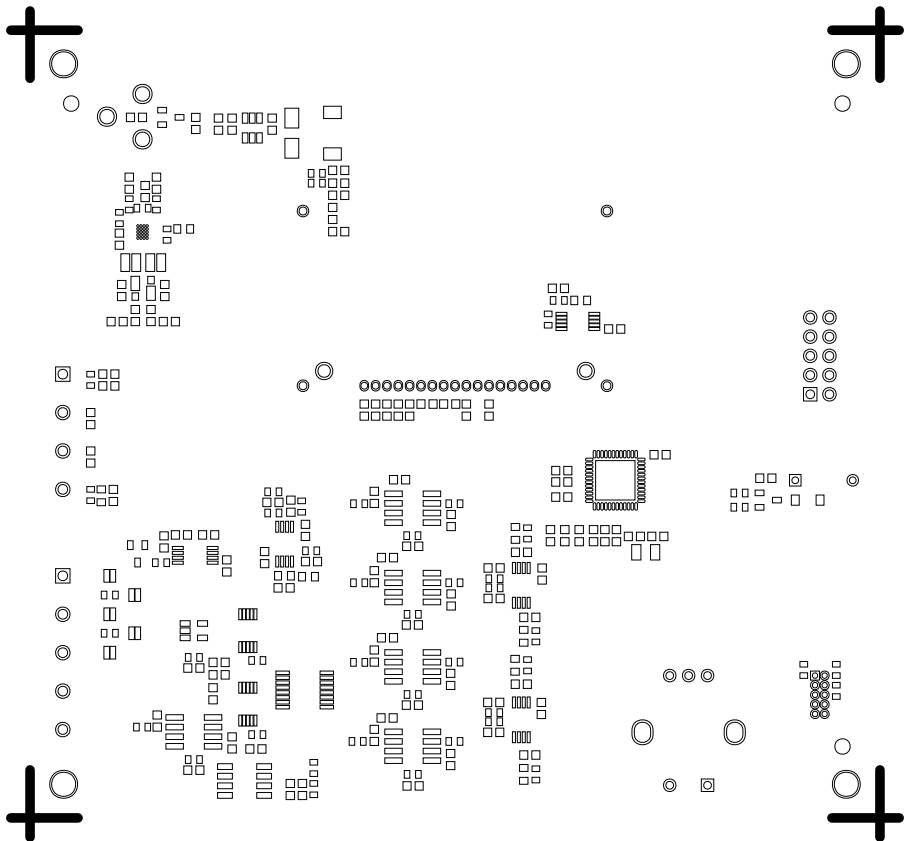
L1 PRIMARY
08-059785-01
REV C



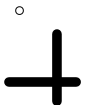
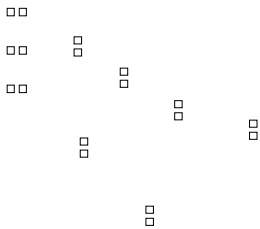
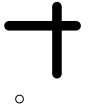
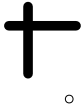
L2 SECONDARY
08-059785-02
REV C



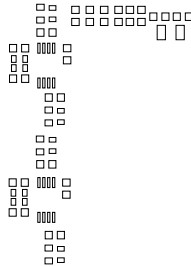
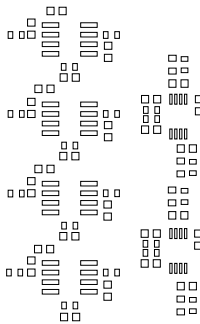
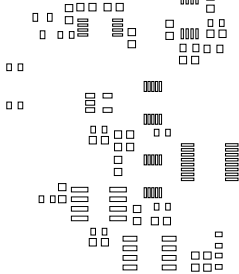
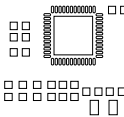
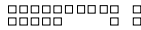
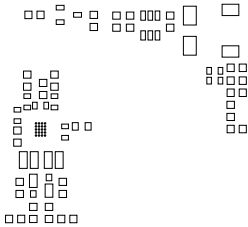
SOLDERMASK SECONDARY
08-059785-06
REV C



PASTEMASK PRIMARY
08-059785-07
REV C



PASTEMASK SECONDARY
08-059785-08
REV C



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